

Title (en)  
ELECTRICAL CONNECTION ARRANGEMENT

Title (de)  
ELEKTRISCHE VERBINDUNGSANORDNUNG

Title (fr)  
ENSEMBLE DE LIAISON ÉLECTRIQUE

Publication  
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Application  
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Abstract (en)  
[origin: WO2015067347A1] The invention relates to a connection arrangement (10) for electrically connecting at least one sensor (12) or actuator to at least one conductor track (22) on a printed circuit board (24), wherein the at least one sensor (12) or actuator has at least one compression spring (18) for electrically conductive connection, and the at least one compression spring (18) is arranged between the at least one sensor (12) or actuator and the printed circuit board (24) so as to have an initial mechanical stress. According to the invention, this connection arrangement (10) has provision for a contact end section (36) – facing the printed circuit board (24) – of the at least one compression spring (18) to ensure reliable electrical connection by abutting a contact plate (20, 70, 80, 90) that is electrically conductively connected to the conductor track (22). As a result, the connection arrangement (10) achieves a high level of electrical contact reliability and has outstanding resistance towards corrosion processes of all kinds, particularly towards environment-related chemical corrosion processes and frictionally corrosive processes. Furthermore, the connection arrangement (10) can also be used without difficulty in the event of parallel use of press-fit technology.

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